

SOT1942-1

WLCSP40, wafer level chip-scale package; 40 bumps; 0.4 mm pitch; 2.25 mm x 3.45 mm x 0.525 mm body (backside coating included)

19 March 2018

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP40
Package type industry code	WLCSP40
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	13-9-2017
Manufacturer package code	SOT1942-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.22	-	2.25	2.28	mm
E	package width	3.42	-	3.45	3.48	mm
A	seated height	0.485	-	0.525	0.565	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	40	-	A/A



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2. Package outline

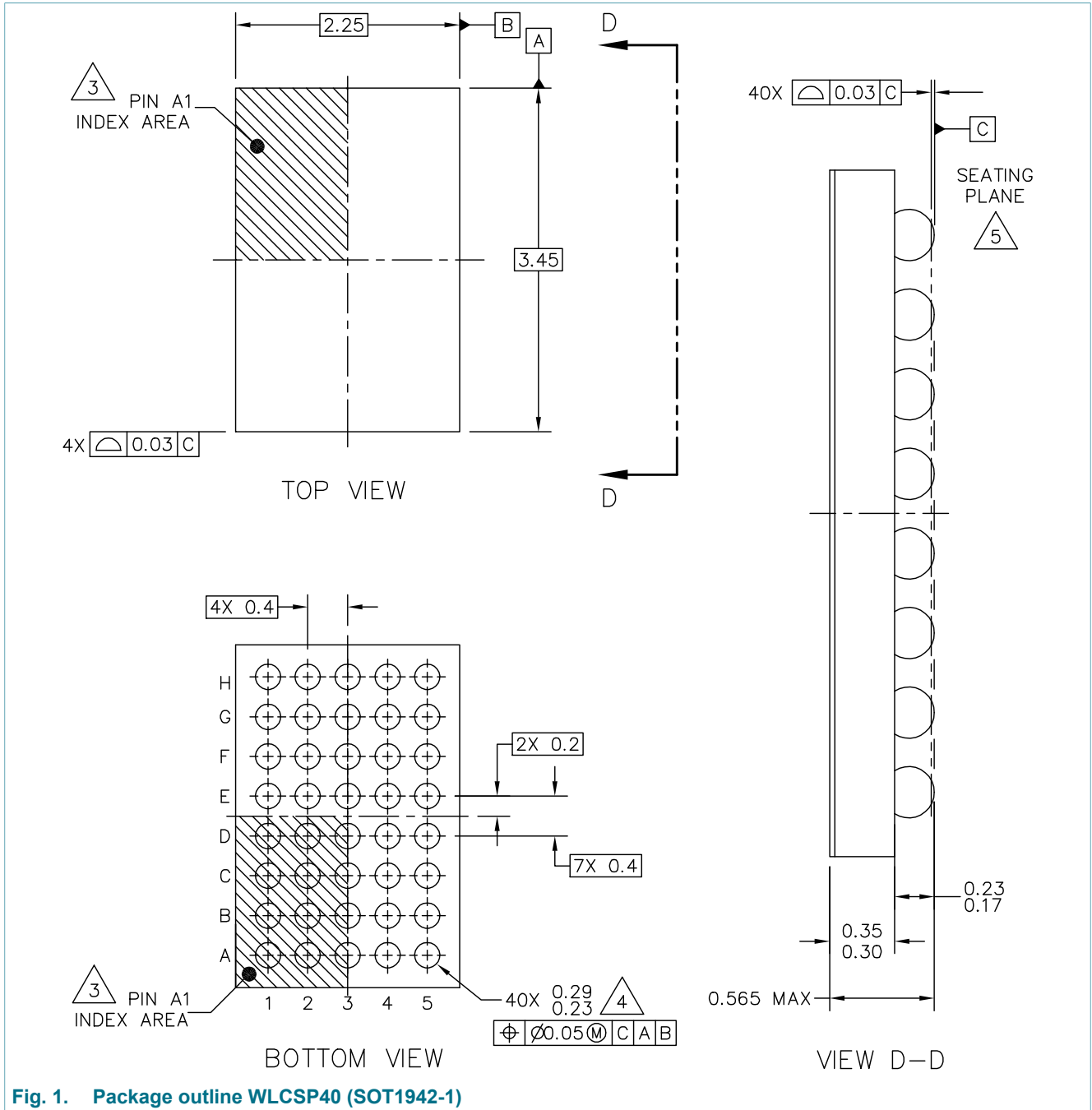


Fig. 1. Package outline WLCSP40 (SOT1942-1)

WLCSP40, wafer level chip-scale package; 40 bumps; 0.4 mm pitch; 2.25 mm x 3.45 mm x 0.525 mm
body (backside coating included)

NOTES:




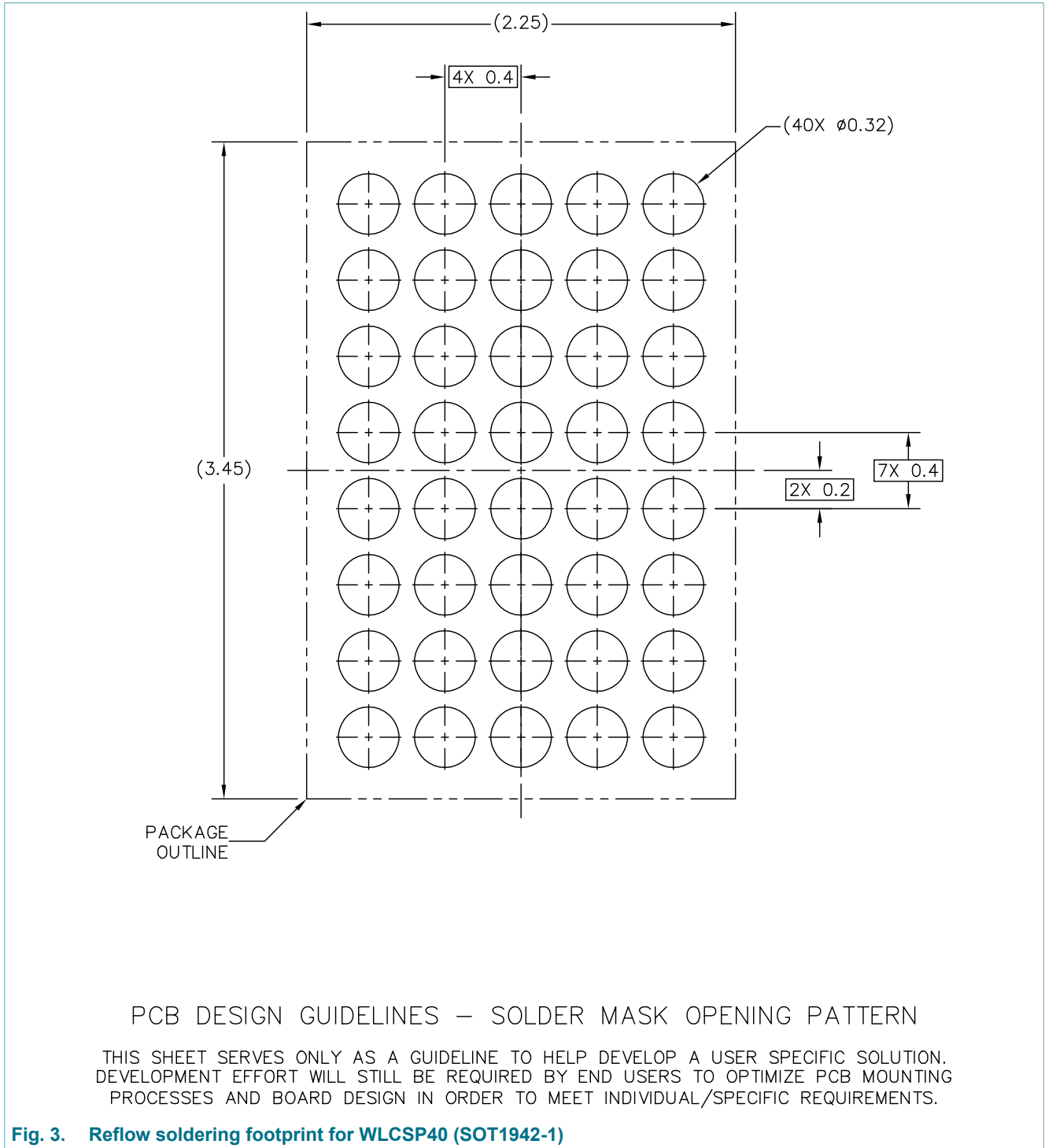
1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3.  PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4.  MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5.  DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

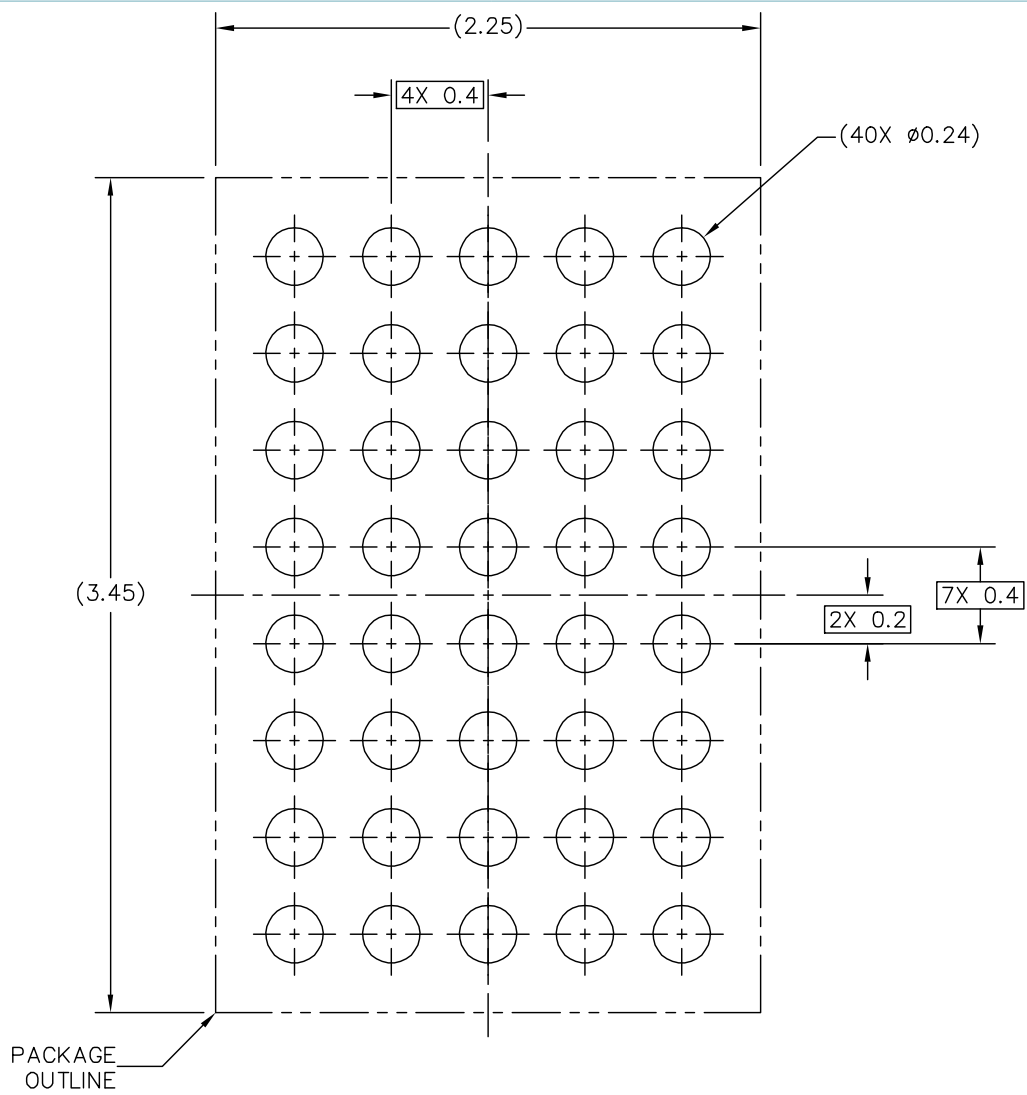
Fig. 2. Package outline note WLCSP40 (SOT1942-1)

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3. Soldering



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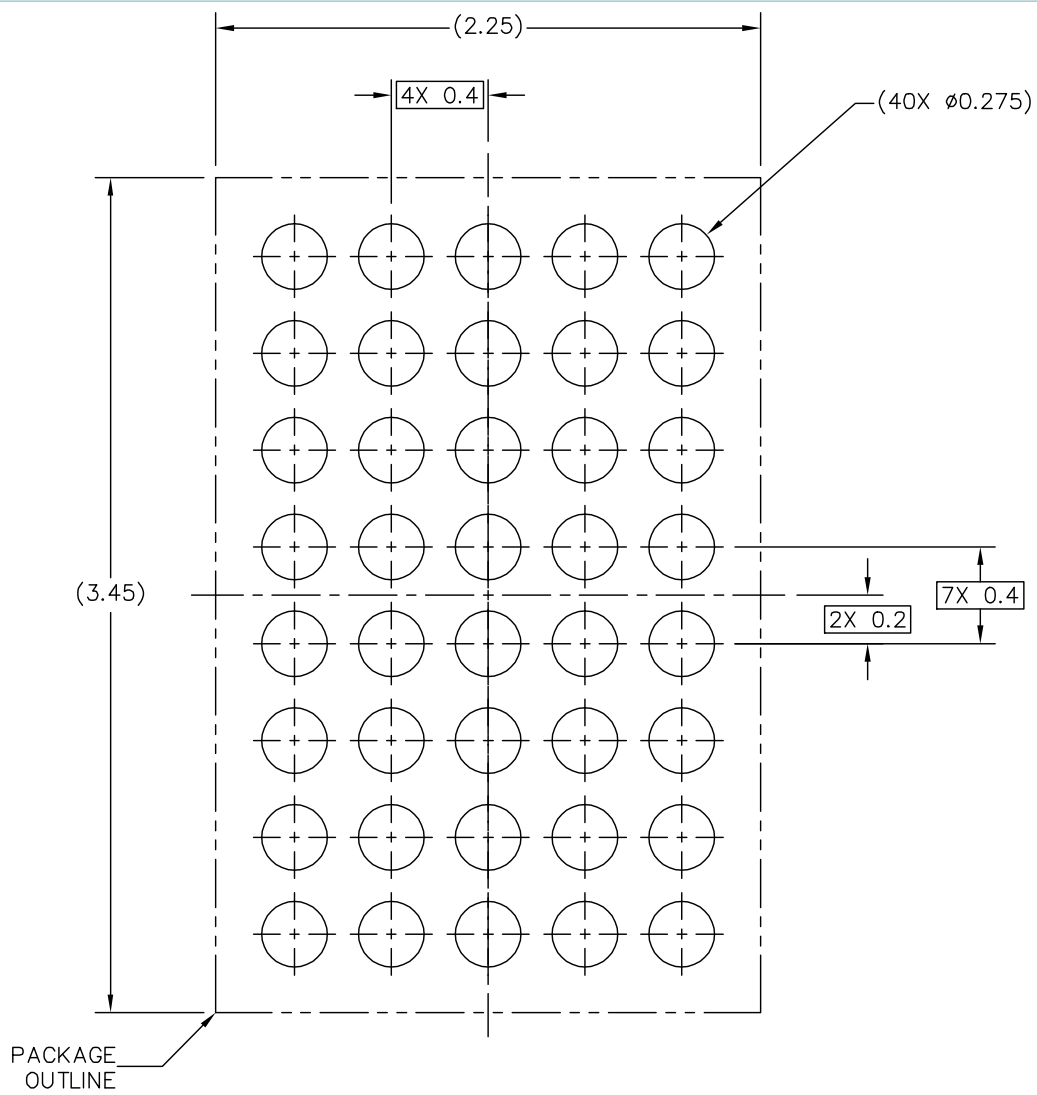


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Fig. 4. Reflow soldering footprint part2 for WLCSP40 (SOT1942-1)

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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 5. Reflow soldering footprint part3 for WLCSP40 (SOT1942-1)

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4. Legal information

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